

Achieves high productivity for sapphire, lithium tantalate, and MEMS processing

Φ200 mm Stealth Dicing™ SDBG SDTT

- DFL7341 is a fully automatic laser saw for $\Phi 8$ -inch wafers which has seen wide used in applications such as LED sapphire substrates and silicon microphones.
- Stealth Dicing™ process makes it possible for brittle materials such as SiC and GaN to be singulated without chipping.
- This is a completely dry process, making it suitable for processing devices such as MEMS that are susceptible to water damage.





Height adjustment function

Stealth Dicing™ process can be performed based on the wafer surface height, making it possible to reliably process wafers with significant warpage.

Wafer shape recognition

Wafer shape is measured using a high-resolution sensor to singulate at the optimal processing area.

Compatibility with various materials

High-quality processing can be achieved for sapphire, SiC, and GaAs using laser oscillators suited for each material.

Specifications

Specification		Unit	
Processing method		-	Stealth Dicing™
Max. workpiece size		mm	Ф200
X-axis (Chuck table)	Processing range	mm	210
	Moving speed	mm/s	1 ~ 1,000
Y-axis (Chuck table)	Processing range	mm	210
	Index step	mm	0.0001
	Positioning accuracy	mm	0.003/210 (Single error)0.002/5
Z-axis	Moving resolution	mm	0.0001
	Repeatability accuracy	mm	0.001
θ-axis (Chuck table)	Max. rotating angle	deg	380
Machine dimensions (W×D×H)		mm	950 × 1,732 × 1,800
Machine weight		kg	Approx. 1,800

^{*}Product appearance, features, specifications, and other details may change due to technical modifications.

Product Lineup



DFL7362

Machine typeFully AutomaticMethodStealth Dicing™

Machine dimentions (W

× D × H) 1,600 × 2,755 × 1,800

Machine weight (kg) 2,850

^{*}Please read the standard specification sheet thoroughly before use.



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